



DCR4880M42

Phase Control Thyristor

DS5943-5 February 2019 (LN37316)

FEATURES

- Double Side Cooling
- High Surge Capability

APPLICATIONS

- High Power Drives
- High Voltage Power Supplies
- Static Switches

VOLTAGE RATINGS

Part and Ordering Number	Repetitive Peak Voltages V _{DRM} and V _{RRM} V	Conditions
DCR4880M42* DCR4880M40 DCR4880M35	4200 4000 3500	$\begin{split} T_{vj} = -40^{\circ}\text{C to } 125^{\circ}\text{C}, \\ I_{DRM} = I_{RRM} = 300\text{mA}, \\ V_{DRM}, V_{RRM} t_p = 10\text{ms}, \\ V_{DSM} \& V_{RSM} = \\ V_{DRM} \& V_{RRM} + 100V \\ respectively \end{split}$

Lower voltage grades available. *4100V @ -40°C, 4200V @ 0°C

ORDERING INFORMATION

When ordering, select the required part number shown in the Voltage Ratings selection table.

For example:

DCR4880M42

Note: Please use the complete part number when ordering and quote this number in any future correspondence relating to your order.

KEY PARAMETERS

 $\begin{array}{lll} V_{DRM} & 4200V \\ I_{T(AV)} & 4880A \\ I_{TSM} & 60800A \\ dV/dt^* & 2000V/\mu s \\ dI/dt & 400A/\mu s \end{array}$

* Higher dV/dt selections available

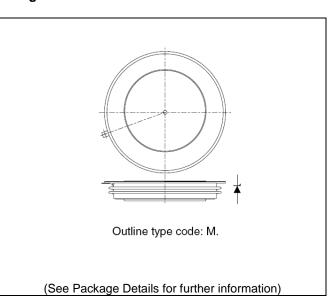


Fig. 1 Package outline





CURRENT RATINGS

$T_{case} = 60$ °C unless stated otherwise

Symbol	Parameter	Test Conditions	Max.	Units
Double Si	de Cooled			
I _{T(AV)}	Mean on-state current	Half wave resistive load	4880	А
I _{T(RMS)}	RMS value	-	7665	А
I _T	Continuous (direct) on-state current	-	7020	А

SURGE RATINGS

Symbol	Parameter	Test Conditions	Max.	Units
I _{TSM}	Surge (non-repetitive) on-state current	10ms half sine, T _{case} = 125°C	60.8	kA
l ² t	I ² t for fusing	$V_R = 0$	18.48	MA ² s

THERMAL AND MECHANICAL RATINGS

Symbol	Parameter	Test Conditions		Min.	Max.	Units
R _{th(j-c)}	Thermal resistance – junction to case	Double side cooled	DC	-	0.00518	°C/W
		Single side cooled	Anode DC	-	0.01012	°C/W
			Cathode DC	-	0.01080	°C/W
R _{th(c-h)}	Thermal resistance – case to heatsink	Clamping force 83.0kN	Double side	-	0.001	°C/W
		(with mounting compound)	Single side	-	0.002	°C/W
T_{vj}	Virtual junction temperature	Blocking V _{DRM} / _{VRRM}		-	125	°C
T _{stg}	Storage temperature range			-55	125	°C
F _m	Clamping force			74.0	91.0	kN





DYNAMIC CHARACTERISTICS

Symbol	Parameter	Test Conditions		Min.	Max.	Units
I _{RRM} /I _{DRM}	Peak reverse and off-state current	At V _{RRM} /V _{DRM} , T _{case} = 125°C		-	300	mA
dV/dt	Max. linear rate of rise of off-state voltage	To 67% V _{DRM} , T _j = 125°C, ga	ate open	-	2000	V/µs
dl/dt	Rate of rise of on-state current	From 67% V _{DRM} to 2x I _{T(AV)}	Repetitive 50Hz	-	200	A/µs
		Gate source 30V, 10Ω,	Non-repetitive	-	500	A/µs
		$t_r < 0.5 \mu s, T_j = 125^{\circ}C$				
$V_{T(TO)}$	Threshold voltage – Low level	500 to 2200A at T _{case} = 125°	С	-	0.75	V
	Threshold voltage – High level	2200 to 8000A at T _{case} = 125	°C	-	0.92	V
r _T	On-state slope resistance – Low level	500 to 2200A at T _{case} = 125°	С	-	0.205	mΩ
	On-state slope resistance – High level	2200 to 8000A at T _{case} = 125°C		-	0.122	mΩ
t _{gd}	Delay time	$V_D = 67\% V_{DRM}$, gate source 30V, 10Ω		-	3	μs
		$t_r = 0.5 \mu s, T_j = 25^{\circ}C$				
tq	Turn-off time	T_j = 125°C, 5000A V_R = 200V, dl/dt = 5 A/ μ s,			900	μs
		dV _{DR} /dt = 20V/μs linear				
Qs	Stored charge	- I _T = 3000A, T _j = 125°C, dI/dt – 1A/μs, V _{Rpeak} ~3100V, V _R ~ 2100V		2920	4875	μC
I _{RR}	Reverse recovery current			42	57	А
IL	Latching current	$T_j = 25$ °C, $V_D = 5V$		-	3	А
I _H	Holding current	$T_j = 25$ °C, $R_{G-K} = \infty$, $I_{TM} = 500$ A, $I_T = 5$ A		-	300	mA



GATE TRIGGER CHARACTERISTICS AND RATINGS

Symbol	Parameter	Test Conditions	Max.	Units
V_{GT}	Gate trigger voltage	$V_{DRM} = 5V$, $T_{case} = 25$ °C	1.5	V
V_{GD}	Gate non-trigger voltage	At 50% V _{DRM} , T _{case} = 125°C	0.4	V
I _{GT}	Gate trigger current	$V_{DRM} = 5V$, $T_{case} = 25$ °C	400	mA
I_{GD}	Gate non-trigger current	At 50% V _{DRM} , T _{case} = 125°C	10	mA

CURVES

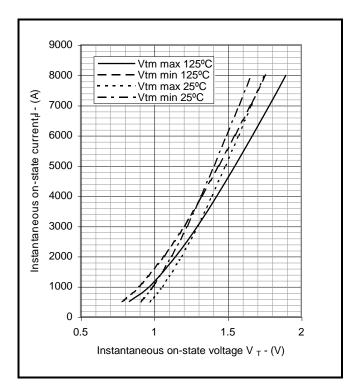


Fig.2 Maximum & minimum on-state characteristics

V_{TM} EQUATION

 $V_{TM} = A + BIn (I_T) + C.I_T + D.\sqrt{I_T}$

Where A = -0.208640

B = 0.171688

C = 0.000113

D = - 0.003842

these values are valid for $T_j = 125$ °C for $I_T 500$ A to 8000A

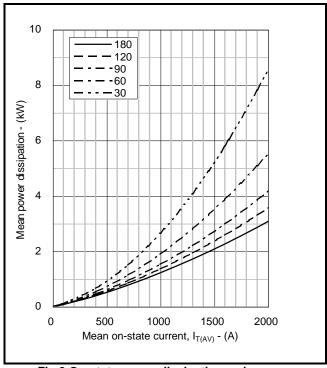


Fig.3 On-state power dissipation - sine wave

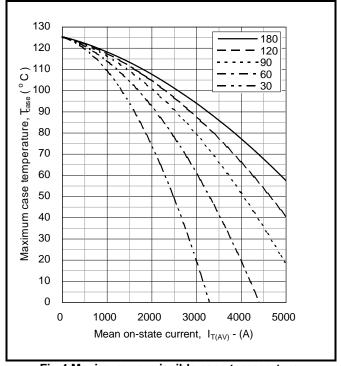


Fig.4 Maximum permissible case temperature, double side cooled – sine wave

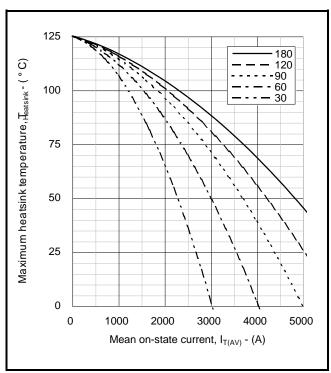


Fig.5 Maximum permissible heatsink temperature, double side cooled – sine wave

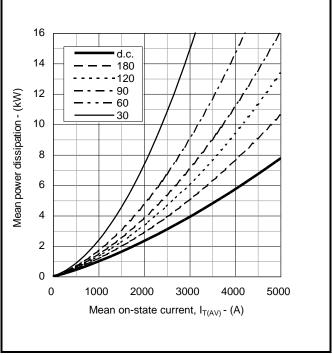


Fig.6 On-state power dissipation - rectangular wave



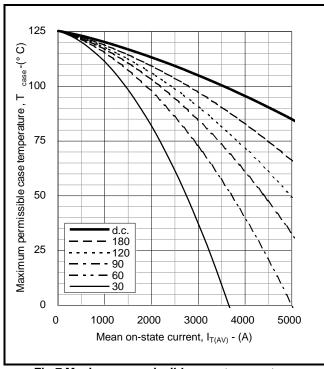


Fig.7 Maximum permissible case temperature, double side cooled – rectangular wave

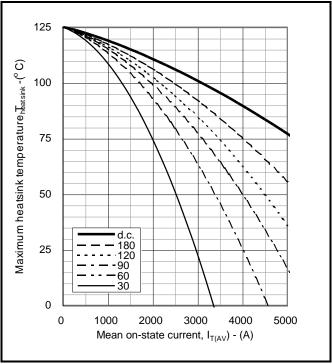
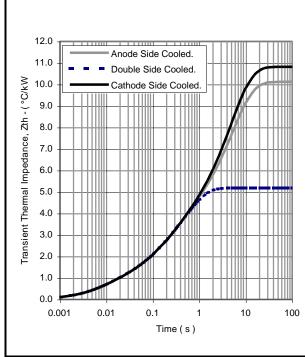


Fig.8 Maximum permissible heatsink temperature, double side cooled – rectangular wave



		1	2	3	4
Double side cooled	R _i (°C/kW)	1.995338	1.242784	1.9448	0.005
Double side cooled	T _i (s)	0.05	0.592935	0.592385	110.5108
Anode side cooled	R _i (°C/kW)	6.092995	1.957372	2.042252	0.035908
Ariode side cooled	T _i (s)	5.459764	0.510898	0.05	110.1735
Cathode side cooled	R _i (°C/kW)	6.856845	1.876401	2.062845	0.025343
Catrioue side cooled	T: (s)	5.181139	0.557321	0.05	110.1546

$$Z_{th} = \sum_{i=1}^{i=4} [R_i \times (1 - \exp(T/T_i))]$$

$\Delta R_{th(j-c)}$ Conduction

Tables show the increments of thermal resistance $R_{\text{th(j-c)}}$ when the device operates at conduction angles other than d.c.

Double side cooling				
	ΔZ_{th} (z)			
θ°	sine.	rect.		
180	0.51	0.36		
120	0.57	0.49		
90	0.64	0.56		
60	0.70	0.63		
30	0.74	0.71		
15	0.76	0.74		

Anode Side Cooling				
	ΔZ_{th} (z)			
θ°	sine.	rect.		
180	0.51	0.36		
120	0.58	0.50		
90	0.65	0.57		
60	0.71	0.64		
30	0.75	0.71		
15	0.77	0.75		

Cathode Sided Cooling			
	$\Delta Z_{th}(z)$		
θ°	sine.	rect.	
180	0.51	0.36	
120	0.58	0.50	
90	0.65	0.57	
60	0.71	0.64	
30	0.75	0.71	
4.5	0.77	0.75	

Fig.9 Maximum (limit) transient thermal impedance - junction to case (°C/kW)

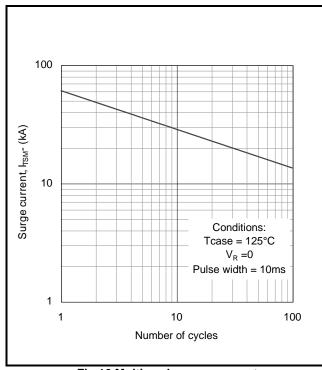


Fig.10 Multi-cycle surge current

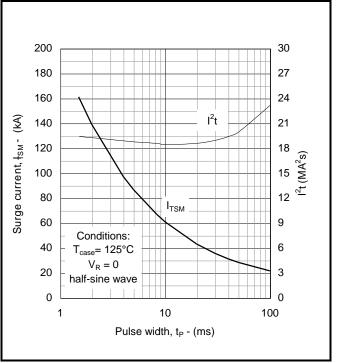


Fig.11 Single-cycle surge current

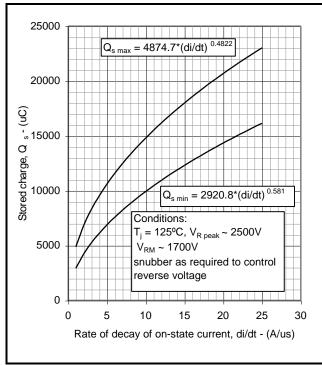


Fig.12 Stored charge

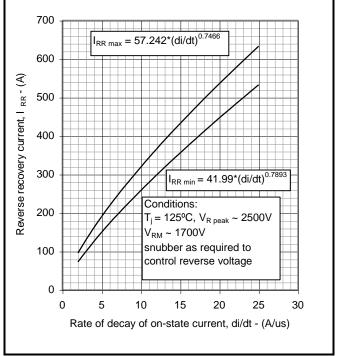


Fig.13 Reverse recovery current

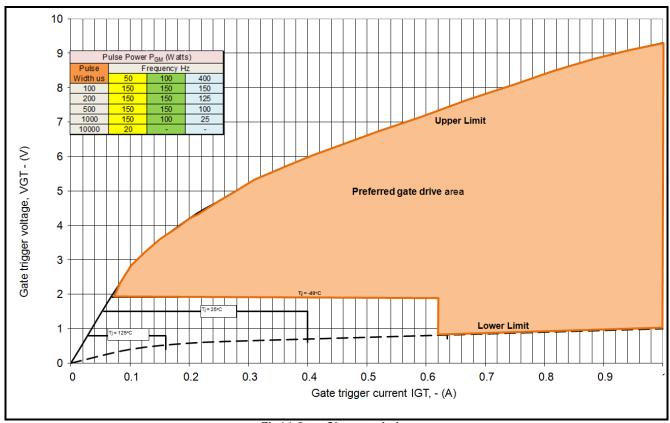


Fig14 Gate Characteristics

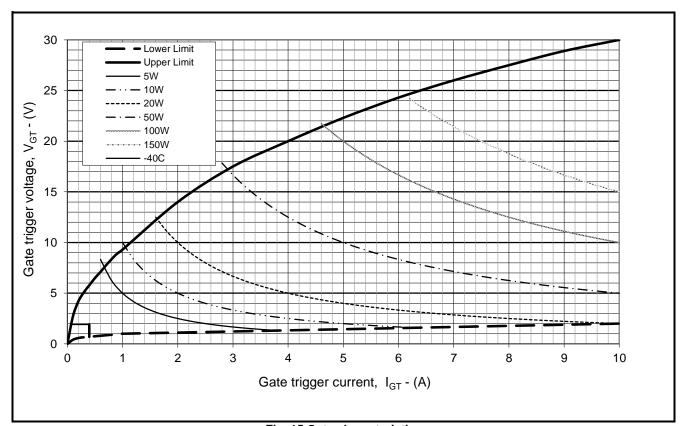


Fig. 15 Gate characteristics





PACKAGE DETAILS

For further package information, please contact Customer Services. All dimensions in mm, unless stated otherwise. DO NOT SCALE.

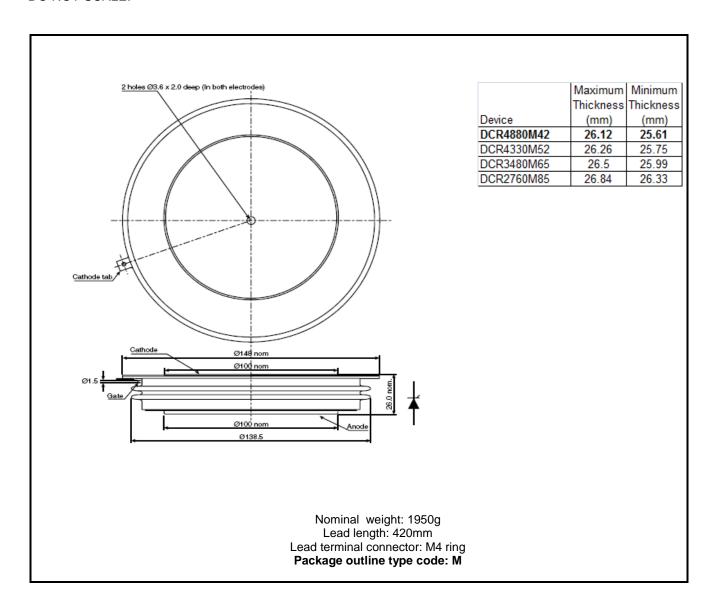


Fig.16 Package outline





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